

100V N-Channel Enhancement Mode MOSFET

Description

The AP5N10MI-C uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 100V$ $I_D = 4.8A$

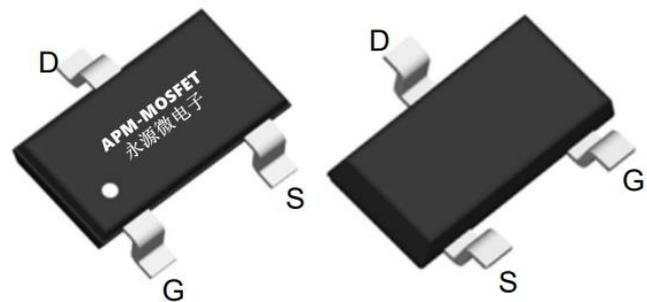
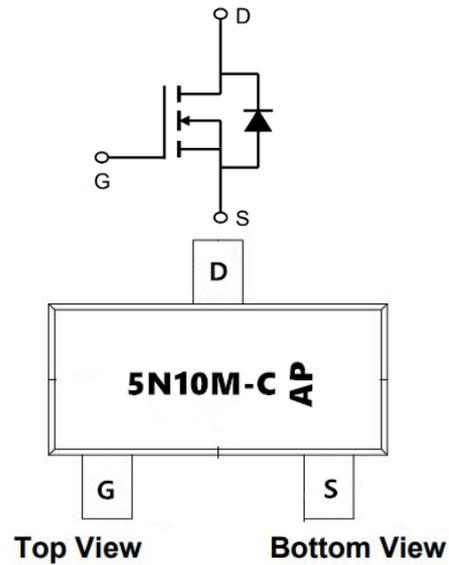
$R_{DS(ON)} < 200m\Omega$ @ $V_{GS}=10V$ (Type: 170m Ω)

Application

LED

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP5N10MI-C	SOT23-3L	5N10MI-C	3000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.8	A
$I_D@T_A=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	2.9	A
IDM	Pulsed Drain Current ²	16	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	3.75	W
TSTG	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
R _{θJA}	Thermal Resistance Junction-ambient ¹	125	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	30	°C/W

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Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	VGS = 0 V, ID = 250 μ A	100	111	-	V
IGSS	Gate Leakage Current	VGS = \pm 20V, VDS = 0V	-	-	\pm 100	nA
IDSS	Drain Cut-off Current	VDS = 100V, VGS = 0V	-	-	1	μ A
VGS(th)	Gate Threshold Voltage	VGS = VDS, ID = 250 μ A	1.2	1.9	2.5	V
RDS(on)	Drain-Source on-state Resistance ³	VGS = 10V, ID = 2A	-	170	200	m Ω
		VGS = 4.5V, ID = 1.5A	-	220	280	
Ciss	Input Capacitance	VGS = 0V, VDS = 50V, f = 1MHz	-	440	-	pF
Coss	Output Capacitance		-	14	-	pF
Crss	Reverse Transfer Capacitance		-	10	-	pF
Qg	Total gate charge	VGS = 10V, VDS = 50V, ID = 2A	-	5.3	-	nC
Qgs	Gate-source charge		-	1.4	-	nC
Qgd	Gate-drain charge		-	1.8	-	nC
td(on)	Turn-on Time	VGS = 10V, VDD = 50V, RG = 1 Ω , ID = 2A	-	14	-	ns
tf	Rise time		-	54	-	ns
td(off)	Turn-off Time		-	18	-	ns
tf	Fall time		-	11	-	ns
VSD	Body Diode Voltage ³	IS = 1A, VGS = 0V	-	-	1.2	V
IS	Continuous Source Current		-	-	2	A

Note :

- 1、 The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width \cong 300us , duty cycle \cong 2%
- 3、 The power dissipation is limited by 150 $^{\circ}$ C junction temperature
- 4、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

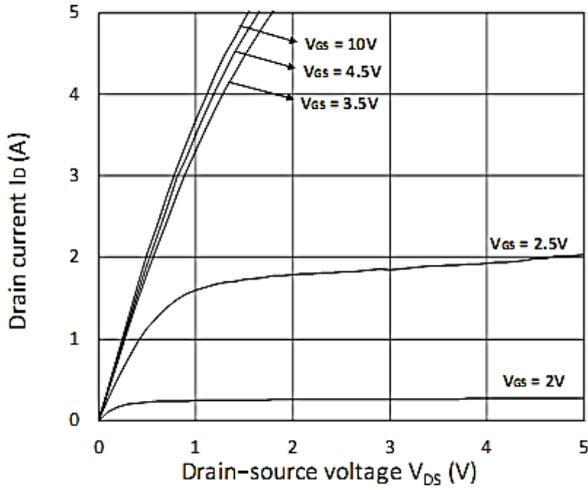


Figure 1. Output Characteristics

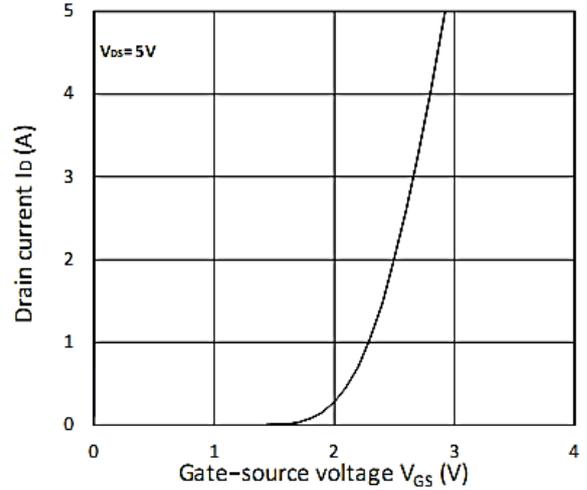


Figure 2. Transfer Characteristics

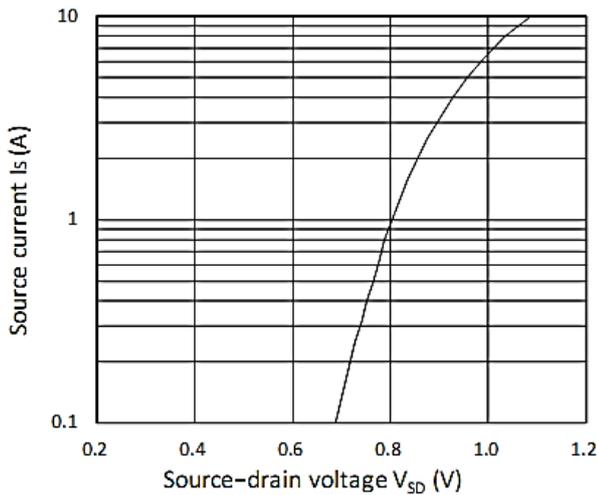


Figure 3. Forward Characteristics of Reverse

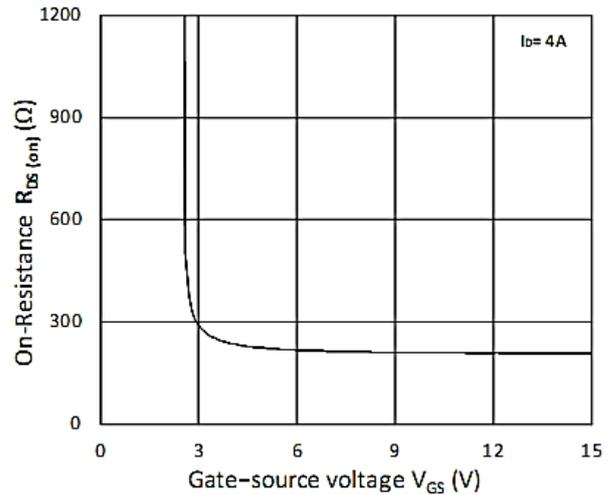


Figure 4. R_{DS(ON)} vs. V_{GS}

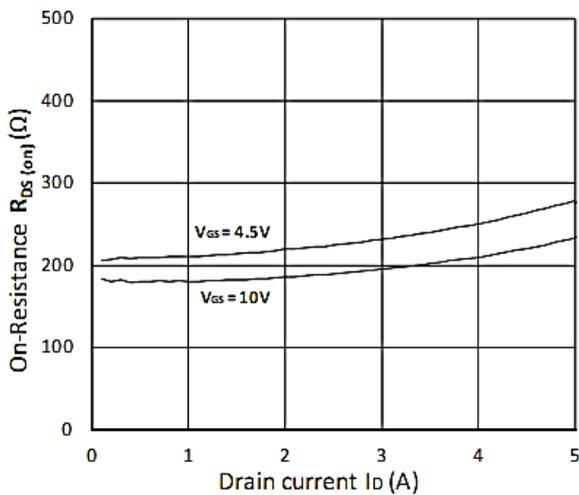


Figure 5. R_{DS(ON)} vs. I_D

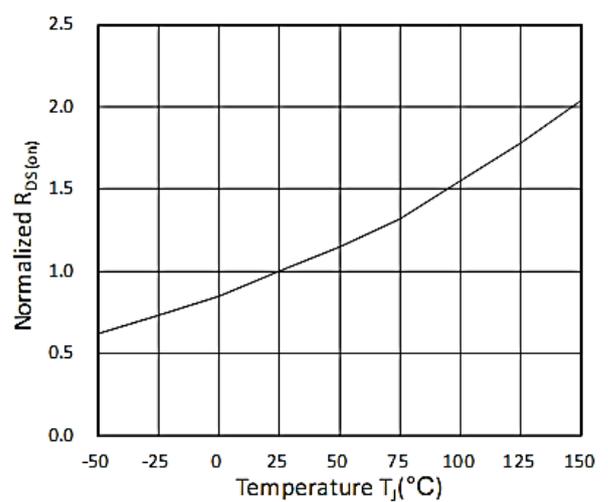


Figure 6. Normalized R_{DS(ON)} vs. Temperature

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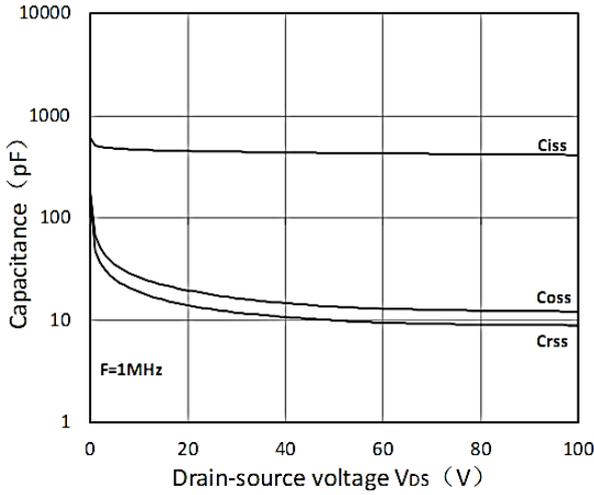


Figure 7. Capacitance Characteristics

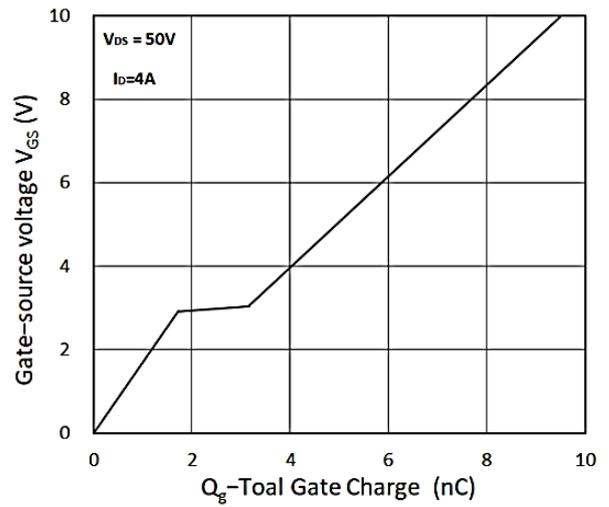


Figure 8. Gate Charge Characteristics

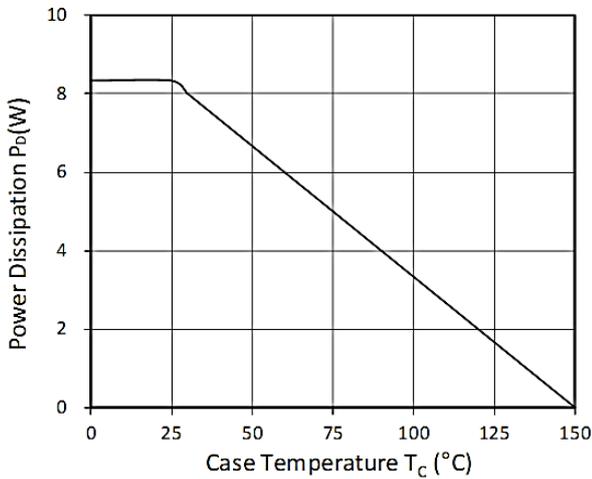


Figure 9. Power Dissipation

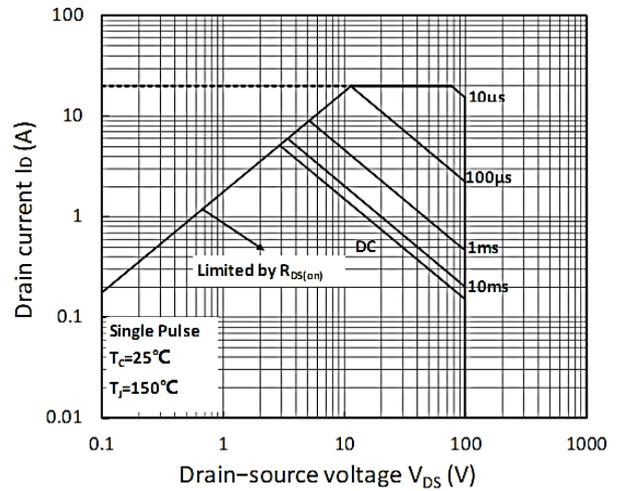


Figure 10. Safe Operating Area

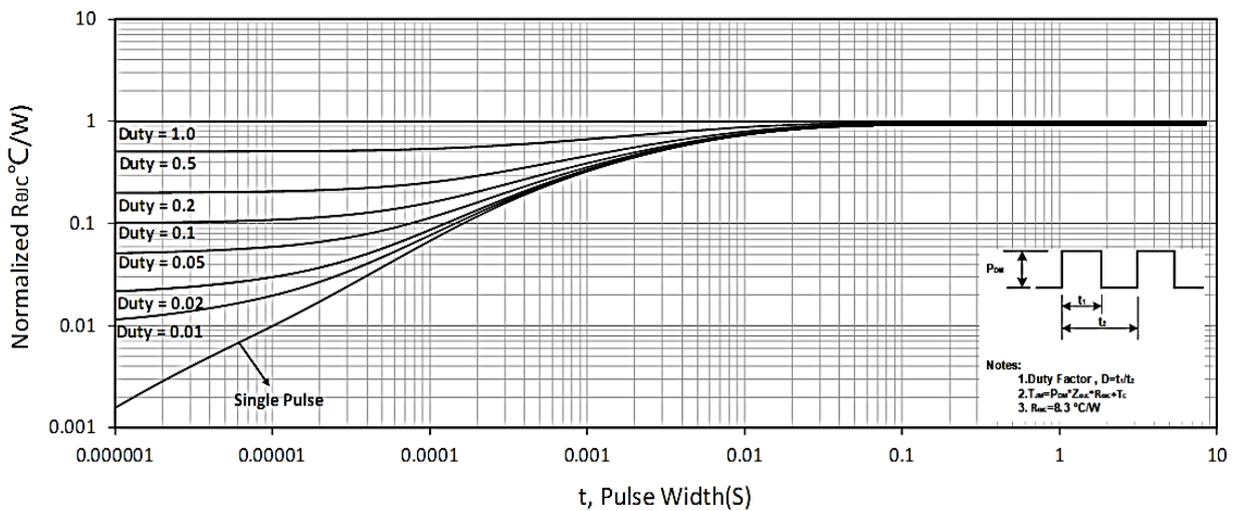
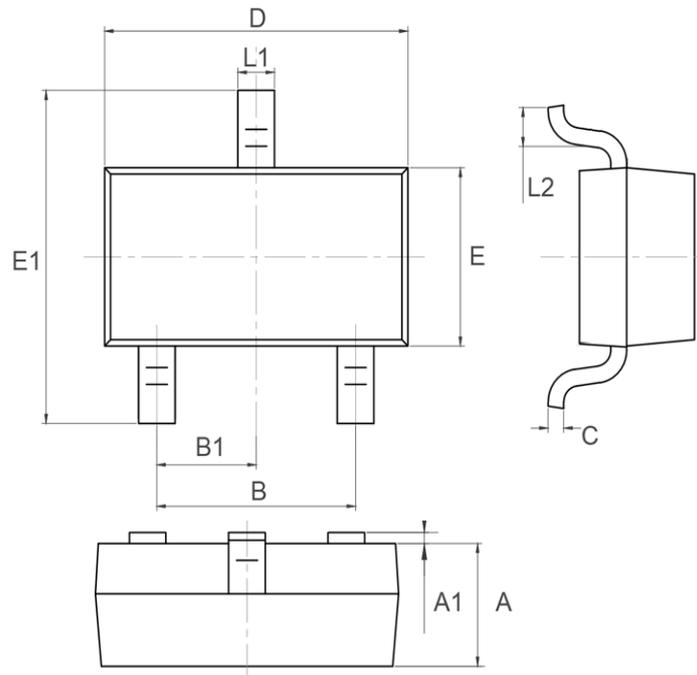


Figure 11. Normalized Maximum Transient Thermal Impedance

Package Mechanical Data-SOT23-3L-Single


Symbol	Dim in mm		
	Min	Typ	Max
A	1	1.1	1.2
A1	0	0.05	0.1
B	1.8	1.9	2
B1	0.95TYP		
C	0.1	0.15	0.2
D	2.82	2.92	3.02
E	1.5	1.6	1.7
E1	2.65	2.8	2.95
L1	0.3	0.4	0.5
L2	0.3	0.45	0.6

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Edition	Date	Change
REV1.0	2025/5/1	Initial release

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